

DR124

High power density, high efficiency, low profile shielded drum core power inductors



Product features

- Low profile surface mount inductor
- 12.5 mm x 12.5 mm x 4.5 mm shielded drum core
- Inductance range from 0.47 μ H to 1000 μ H
- Current range from 0.44 A to 24.4 A
- Frequency range up to 1 MHz
- Ferrite core material

Applications

- Notebook power
- LCD panels
- Desktop and servers
- DVD players and portable power devices
- DC-DC Converters
- Buck, boost, forward, and resonant converters
- Noise filtering and filter chokes

Environmental Data

- Storage temperature range (Component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant



Product specifications

Part Number	Rated Inductance (μH)	OCL ¹ μH±20%	I _{rms} ² (A)	I _{sat} ³ (A)	DCR mΩ @20°C Typ	DCR mΩ @ +20°C Max	K-factor ⁴
DR124-R47-R	0.47	0.42	16.0	24.40	2.2	2.7	17.51
DR124-1R0-R	1.0	0.83	13.9	18.00	3.00	3.6	12.50
DR124-1R5-R	1.5	1.37	11.1	14.00	4.75	5.7	9.73
DR124-2R2-R	2.2	2.04	9.1	11.45	5.92	7.1	7.96
DR124-3R9-R	3.9	3.80	7.0	8.40	12.50	15.0	5.84
DR124-4R7-R	4.7	4.88	6.5	7.65	13.50	16.2	5.15
DR124-6R8-R	6.8	6.10	5.6	6.47	18.06	21.7	4.61
DR124-8R2-R	8.2	7.45	5.2	6.22	21.67	26.0	4.17
DR124-100-R	10	8.94	4.5	5.80	23.33	28.0	3.81
DR124-120-R	12	11.5	4.1	4.96	31.67	38.0	3.50
DR124-150-R	15	14.2	3.6	4.62	37.30	44.8	3.02
DR124-180-R	18	16.2	3.4	4.32	46.97	56.4	2.82
DR124-220-R	22	20.7	3.2	3.83	53.99	64.8	2.50
DR124-270-R	27	25.7	2.8	3.44	66.67	80.0	2.24
DR124-330-R	33	31.2	2.6	3.12	80.83	97.0	2.04
DR124-390-R	39	37.3	2.3	2.85	110.00	132.0	1.86
DR124-470-R	47	44.0	2.2	2.63	124.66	149.6	1.72
DR124-560-R	56	54.9	2.0	2.35	144.32	173.2	1.54
DR124-680-R	68	67.1	1.8	2.13	183.33	220.0	1.39
DR124-820-R	82	80.5	1.7	1.94	212.72	255.3	1.27
DR124-101-R	100	95.1	1.5	1.79	256.67	308.0	1.17
DR124-121-R	120	111	1.3	1.65	311.18	373.4	1.08
DR124-151-R	150	146	1.3	1.44	371.02	445.2	0.94
DR124-181-R	180	179	1.1	1.30	501.66	602.0	0.87
DR124-221-R	220	216	1.0	1.15	558.00	669.6	0.77
DR124-271-R	270	256	0.88	1.09	725.00	870.0	0.71
DR124-331-R	330	327	0.83	0.92	825.00	990.0	0.63
DR124-471-R	470	460	0.68	0.74	1242.50	1491.0	0.53
DR124-681-R	680	669	0.56	0.65	1845.83	2215.0	0.45
DR124-821-R	820	825	0.53	0.62	2109.17	2351.0	0.40
DR124-102-R	1000	998	0.44	0.53	2898.00	3477.00	0.37

1. Open Circuit Inductance Test Parameters: 100 kHz, 0.25 V, 0.0 Adc.
2. I_{rms}²: DC current for an approximate ΔT of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application.
3. I_{sat}³: Amps peak for approximately 25% rolloff (@ +25 °C).

4. K-factor: Used to determine B_{pp} for core loss (see graph).
B_{pp} = K*L*ΔI, B_{pp} (mT), K: (K factor from table), L: (Inductance in μH), ΔI (Peak to peak ripple current in Amps).
5. Part Number Definition: DR124-xxx-R
- DR124 = Product code and size; -xxx = Inductance value in uH;
- R = decimal point; If no R is present, third character = # of zeros.
- "-R" suffix = RoHS compliant

DR124
 High power density, high efficiency, low profile shielded drum
 core power inductors

Dimensions- mm



Dimensions are in millimeters.
 Do not route traces or vias underneath the inductor.

wwllyy = Date code, R = Revision level.

Packaging- mm



Parts packaged on 13" Diameter reel, 750 parts per reel.

Temperature rise vs. total loss



Core loss vs. Bp-p



Inductance characteristics



Solder reflow profile



Table 1 - Standard SnPb Solder (Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JEDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T _{smin})	100°C	150°C
• Temperature max. (T _{smax})	150°C	200°C
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T _{smax} to T _p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T _L)	183°C	217°C
Time at liquidous (t _L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T _p)*	Table 1	Table 2
Time (t _p)** within 5 °C of the specified classification temperature (T _c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T _p to T _{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

Eaton reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Eaton also reserves the right to change or update, without notice, any technical information contained in this bulletin.

Eaton
Electronics Division
 1000 Eaton Boulevard
 Cleveland, OH 44122
 United States
www.eaton.com/electronics

© 2019 Eaton
 All Rights Reserved
 Printed in USA
 Publication No. 4141 BU-SB14114
 March 2019

Eaton is a registered trademark.

All other trademarks are property of their respective owners.

